

# **SLOVENSKI STANDARD SIST EN 60664-3:2004/A1:2010**

01-november-2010

Uskladitev izolacije za opremo v okviru nizkonapetostnih sistemov - 3. del: Zaščita pred onesnaženjem s prevlekami, zapiranjem v ohišja ali zalivanjem - Dopolnilo A1 (IEC 60664-3:2003/A1:2010)

Insulation coordination for equipment within low-voltage systems - Part 3: Use of coating, potting or moulding for protection against pollution (IEC 60664-3:2003/A1:2010)

Isolationskoordination für elektrische Betriebsmittel in Niederspannungsanlagen - Teil 3: Anwendung von Beschichtungen, Eingießen oder Vergießen zum Schutz gegen Verschmutzung (IEC 60664-3:2003/A1:2010) S. Iten. a1

Coordination de l'isolement des matériels dans les systèmes (réseaux) à basse tension - Partie 3: Utilisation de revêtement d'empotage ou de moulage pour la protection contre la pollution (CEI 60664-3:2003/A1:2010)

Ta slovenski standard je istoveten z: EN 60664-3:2003/A1:2010

ICS:

29.080.30 Izolacijski sistemi Insulation systems

SIST EN 60664-3:2004/A1:2010 en

SIST EN 60664-3:2004/A1:2010

### iTeh STANDARD PREVIEW (standards.iteh.ai)

SIST EN 60664-3:2004/A1:2010 https://standards.iteh.ai/catalog/standards/sist/ab34df77-dfcc-4967-9d36-0c28ed9a1acc/sist-en-60664-3-2004-a1-2010

**EUROPEAN STANDARD** 

EN 60664-3/A1

NORME FUROPÉENNE **EUROPÄISCHE NORM** 

June 2010

ICS 29.080.30

**English version** 

Insulation coordination for equipment within low-voltage systems -Part 3: Use of coating, potting or moulding for protection against pollution (IEC 60664-3:2003/A1:2010)

Coordination de l'isolement des matériels dans les systèmes (réseaux) à basse tension -Partie 3: Utilisation de revêtement.

d'empotage ou de moulage pour la protection contre la pollution (CEI 60664-3:2003/A1:2010)

Isolationskoordination für elektrische Betriebsmittel in Niederspannungsanlagen -Teil 3: Anwendung von Beschichtungen, Eingießen oder Vergießen zum Schutz gegen Verschmutzung (IEC 60664-3:2003/A1:2010)

### iTeh STANDARD PREVIEW (standards.iteh.ai)

This amendment A1 modifies the European Standard EN 60664-3:2003; it was approved by CENELEC on 2010-06-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this amendment the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This amendment exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

### **CENELEC**

European Committee for Electrotechnical Standardization Comité Européen de Normalisation Electrotechnique Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

### **Foreword**

The text of document 109/79/FDIS, future amendment 1 to IEC 60664-3:2003, prepared by IEC TC 109, Insulation co-ordination for low-voltage equipment, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as amendment A1 to EN 60664-3:2003 on 2010-06-01.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

The following dates were fixed:

 latest date by which the amendment has to be implemented at national level by publication of an identical national standard or by endorsement

(dop) 2011-03-01

 latest date by which the national standards conflicting with the amendment have to be withdrawn

(dow) 2013-06-01

Annex ZA has been added by CENELEC.

### **Endorsement notice**

The text of amendment 1:2010 to the International Standard IEC 60664-3:2003 was approved by CENELEC as an amendment to the European Standard without any modification.

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SIST ENBIbliography 2010

https://standards.iteh.ai/catalog/standards/sist/ab34df77-dfcc-4967-9d36

Replace the existing text by the following note for the standard indicated:

IEC 60194:2006 NOTE Harmonized as EN 60194:2006 (not modified).

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Replace Annex ZA of EN 60664-3:2003 by:

### Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	EN/HD	<u>Year</u>
IEC 60068-2-1	2007	Environmental testing - Part 2-1: Tests - Test A: Cold	EN 60068-2-1	2007
IEC 60068-2-2	2007	Environmental testing - Part 2-2: Tests - Test B: Dry heat	EN 60068-2-2	2007
IEC 60068-2-14	2009	Environmental testing PREVIE Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	2009
IEC 60068-2-78	2001 https://sta		EN 60068-2-78 7-9d36-	2001
IEC 60454-3-1 + A1	1998 2001	Oc28ed9a1acc/sist-en-60664-3-2004-a1-2010 Pressure-sensitive adhesive tapes for electrical purposes - Part 3-1: Specifications for individual materials - PVC film tapes with pressure-sensitive adhesive	EN 60454-3-1 + A1	1998 2001
IEC 60664-1	2007	Insulation coordination for equipment within low-voltage systems - Part 1: Principles, requirements and tests	EN 60664-1	2007
IEC 60664-5	2007	Insulation coordination for equipment within low-voltage systems - Part 5: Comprehensive method for determining clearances and creepage distances equal to or less than 2 mm	EN 60664-5	2007
IEC 61189-2	2006	Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2: Test methods for materials for interconnection structures	EN 61189-2	2006
IEC 61189-3	2007	Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3: Test methods for interconnection structures (printed boards)	EN 61189-3	2008

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61249-2	Series	Materials for printed boards and other interconnecting structures - Part 2: Reinforced base materials, clad and unclad	EN 61249-2	Series
IEC Guide 104	1997	The preparation of safety publications and the use of basic safety publications and group safety publications	; -	-

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<u>SIST EN 60664-3:2004/A1:2010</u> https://standards.iteh.ai/catalog/standards/sist/ab34df77-dfcc-4967-9d36-0c28ed9a1acc/sist-en-60664-3-2004-a1-2010



IEC 60664-3

Edition 2.0 2010-05

## INTERNATIONAL **STANDARD**

## **NORME** INTERNATIONALE

BASIC SAFETY PUBLICATION

PUBLICATION FONDAMENTALE DE SÉCURITÉ

AMENDMENT 1

AMENDEMENT 1 iTeh STANDARD PREVIEW

(standards.iteh.ai)

Insulation coordination for equipment within low-voltage systems -Part 3: Use of coating, potting or moulding for protection against pollution

0c28ed9a1acc/sist-en-60664-3-2004-a1-2010

Coordination de l'isolement des matériels dans les systèmes (réseaux) à basse tension -

Partie 3: Utilisation de revêtement, d'empotage ou de moulage pour la protection contre la pollution

INTERNATIONAL **ELECTROTECHNICAL COMMISSION** 

COMMISSION **ELECTROTECHNIQUE INTERNATIONALE** 

PRICE CODE CODE PRIX

ICS 29.080.30

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60664-3 Amend.1 © IEC:2010

### **FOREWORD**

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This amendment has been prepared by IEC technical committee 109: Insulation coordination for low-voltage equipment.

The text of this amendment is based on the following documents:

FDIS	Report on voting	
109/79/FDIS	109/81/RVD	

Full information on the voting for the approval of this amendment can be found in the report on voting indicated in the above table.

The committee has decided that the contents of this amendment and the base publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- · reconfirmed,
- withdrawn.
- · replaced by a revised edition, or
- amended.

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### 2 Normative references

SIST EN 60664-3:2004/A1:2010

https://standards.iteh.ai/catalog/standards/sist/ab34df77-dfcc-4967-9d36-

Replace the existing text by the following ist-en-60664-3-2004-a1-2010

IEC 60068-2-1:2007, Environmental testing - Part 2-1: Tests - Test A: Cold

IEC 60068-2-2:2007, Environmental testing – Part 2-2: Tests – Test B: Dry heat

IEC 60068-2-14:2009, Environmental testing – Part 2-14: Tests – Test N: Change of temperature

IEC 60068-2-78:2001, Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state

IEC 60454-3-1:1998, Pressure-sensitive adhesive tapes for electrical purposes – Part 3: Specifications for individual materials – Sheet 1: PVC film tapes with pressure-sensitive adhesive
Amendment 1 (2001)

IEC 60664-1:2007, Insulation coordination for equipment within low-voltage systems – Part 1: Principles, requirements and tests

IEC 60664-5:2007, Insulation coordination for equipment within low-voltage systems – Part 5: Comprehensive method for determining clearances and creepage distances equal to or less than 2 mm

IEC 61189-2:2006, Test methods for electrical materials, printed boards and other interconnection structures and assemblies – Part 2:Test methods for materials for interconnection structures

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IEC 61189-3:2007, Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3: Test methods for interconnection structures (printed boards)

IEC 61249-2 (all Parts 2) Materials for printed boards and other interconnecting structures -Reinforced base materials, clad and unclad

IEC Guide 104:2004, The preparation of safety publications and the use of basic safety publications and group safety publications

#### 4.2 Application range regarding environment

Replace, in the second paragraph, "3.3.2.3 ..." by "5.3.2.4 ..."

### 4.4 Dimensioning procedures

Replace in the first paragraph, "3.1 and 3.2 .. " by "5.1 and 5.2 ... "

At the end of the second paragraph add the following sentence:

These values may also be applied to functional insulation.

#### 5.1 General

Add the following note after the first paragraph. PREVIEW

NOTE The suitability of protection is evaluated after the scratch resistance test described in 5.5, the visual examination described in 5.6 and the subsequent conditioning described in 5.7.

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5.5 Scratch resistance test ds.iteh.ai/catalog/standards/sist/ab34df77-dfcc-4967-9d36-

Replace the first paragraph by the following:

NOTE In some cases, scratch resistance test cannot be applied to assemblies protected against pollution by the use of potting or moulding. In such cases, considerations for any alternatively or additional tests may be necessary

Scratches shall be made across five pairs of conducting parts and the intervening separations at points where the insulation will be subject to the maximum electric field strength between conductors.

#### 5.6 Visual examination

Replace the first paragraph by the following:

The specimens shall be visually examined according to test 3V02 in 6.2 of IEC 61189-3:2007.

#### 5.7.2 Dry heat

Replace the footnote in Table 2 by the following:

a) For defined flammability, refer to 8.6 of IEC 61189-2:2006 and the relevant part 2 of IEC 61249.

#### 5.8.3 Insulation resistance between conductors

Replace the first paragraph by the following:

The test shall be carried out according to 10.3 of IEC 61189-3:2007, the voltage specified for test method 3E03 being as close to the working voltage as possible.